

Title (en)
METHOD FOR MANUFACTURING AN ELECTRONIC DEVICE COMPRISING AT LEAST ONE SUPERCONDUCTIVE ZONE AND ASSOCIATED DEVICE

Title (de)
VERFAHREN ZUR HERSTELLUNG EINER ELEKTRONISCHEN VORRICHTUNG MIT MINDESTENS EINER SUPRALEITENDEN ZONE UND ZUGEHÖRIGE VORRICHTUNG

Title (fr)
PROCÉDÉ DE FABRICATION D'UN DISPOSITIF ÉLECTRONIQUE COMPORTANT AU MOINS UNE ZONE SUPRACONDUCTRICE ET DISPOSITIF ASSOCIÉ

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Application
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Abstract (en)
[origin: WO2021156378A1] The invention relates to a method for manufacturing a device, the device comprising a superconductive zone (20) and an insulating zone (22) in accordance with an arrangement, comprising the steps of: - depositing a buffer layer (12) on a portion of a substrate (10), - etching the buffer layer (12) in order to obtain two zones (Z1, Z2), each first zone (Z1) being a zone in which the substrate (10) is covered by the buffer layer (12) and which is intended to form a respective superconductive zone (20), each second zone (Z2) being a zone in which the substrate (10) is exposed to form a respective insulating zone (22), and - depositing a second layer (18) of superconductive material on the whole of the portion of the substrate (10), the first layer (12) being constructed in the form of at least two superimposed sub-layers (14, 16).

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